

# **ESD Protected to $\pm 15\text{kV}$ , 5V, Low Power, High Speed or Slew Rate Limited, RS-485/RS-422 Transceivers**

These Intersil RS-485/RS-422 devices are ESD protected, BiCMOS 5V powered, single transceivers that meet both the RS-485 and RS-422 standards for balanced communication. Each driver output/receiver input is protected against  $\pm 15\text{kV}$  ESD strikes, without latch-up. Unlike competitive devices, this Intersil family is specified for 10% tolerance supplies (4.5V to 5.5V).

The ISL8483E utilizes slew rate limited drivers which reduce EMI, and minimize reflections from improperly terminated transmission lines, or unterminated stubs in multidrop and multipoint applications.

Data rates up to 5Mbps are achievable by using the ISL8485E which features higher slew rates.

Both devices present a "single unit load" to the RS-485 bus, which allows up to 32 transceivers on the network.

Receiver (Rx) inputs feature a "fail-safe if open" design, which ensures a logic high Rx output, if Rx inputs are floating.

Driver (Tx) outputs are short circuit protected, even for voltages exceeding the power supply voltage. Additionally, on-chip thermal shutdown circuitry disables the Tx outputs to prevent damage if power dissipation becomes excessive.

These half duplex configurations multiplex the Rx inputs and Tx outputs to allow transceivers with Rx and Tx disable functions in 8 lead packages.

## **Features**

- RS-485 I/O Pin ESD Protection .....  $\pm 15\text{kV}$  HBM
  - Class 3 ESD Level on all Other Pins .....  $>7\text{kV}$  HBM
- Specified for 10% Tolerance Supplies
- High Data Rate Version (ISL8485E) ..... up to 5Mbps
- Slew Rate Limited Version for Error Free Data Transmission (ISL8483E) ..... up to 250kbps
- Single Unit Load Allows up to 32 Devices on the Bus
- 1nA Low Current Shutdown Mode (ISL8483E)
- Low Quiescent Current:
  - 160 $\mu\text{A}$  (ISL8483E)
  - 340 $\mu\text{A}$  (ISL8485E)
- -7V to +12V Common Mode Input Voltage Range
- Three State Rx and Tx Outputs
- 30ns Propagation Delays, 5ns Skew (ISL8485E)
- Operate from a Single +5V Supply (10% Tolerance)
- Current Limiting and Thermal Shutdown for driver Overload Protection

## **Applications**

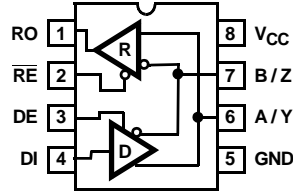
- Factory Automation
- Security Networks
- Building Environmental Control Systems
- Industrial/Process Control Networks
- Level Translators (e.g., RS-232 to RS-422)
- RS-232 "Extension Cords"

**TABLE 1. SUMMARY OF FEATURES**

PART NUMBER	HALF/FULL DUPLEX	NO. OF DEVICES ALLOWED ON BUS	DATA RATE (Mbps)	SLEW-RATE LIMITED?	RECEIVER/DRIVER ENABLE?	QUIESCENT $I_{CC}$ ( $\mu\text{A}$ )	LOW POWER SHUTDOWN?	PIN COUNT
ISL8483E	Half	32	0.25	Yes	Yes	160	Yes	8
ISL8485E	Half	32	5	No	Yes	340	No	8

## Pinout

ISL8483E, ISL8485E (PDIP, SOIC)  
TOP VIEW



## Ordering Information

PART NO. (BRAND)	TEMP. RANGE (°C)	PACKAGE	PKG. DWG. #
ISL8483EIB (8483EIB)	-40 to 85	8 Ld SOIC	M8.15
ISL8483EIB-T (8483EIB)	-40 to 85	8 Ld SOIC Tape and Reel	M8.15
ISL8483EIP	-40 to 85	8 Ld PDIP	E8.3
ISL8485ECB (8485ECB)	0 to 70	8 Ld SOIC	M8.15
ISL8485ECB-T (8485ECB)	0 to 70	8 Ld SOIC Tape and Reel	M8.15
ISL8485ECP	0 to 70	8 Ld PDIP	E8.3
ISL8485EIB (8485EIB)	-40 to 85	8 Ld SOIC	M8.15
ISL8485EIB-T (8485EIB)	-40 to 85	8 Ld SOIC Tape and Reel	M8.15
ISL8485EIP	-40 to 85	8 Ld PDIP	E8.3

## Truth Tables

TRANSMITTING

INPUTS			OUTPUTS	
$\overline{RE}$	DE	DI	Z	Y
X	1	1	0	1
X	1	0	1	0
0	0	X	High-Z	High-Z
1	0	X	High-Z *	High-Z *

\*Shutdown Mode for ISL8483E (see Note 7)

RECEIVING

INPUTS			OUTPUT
$\overline{RE}$	DE	A-B	RO
0	0	$\geq +0.2V$	1
0	0	$\leq -0.2V$	0
0	0	Inputs Open	1
1	0	X	High-Z*
1	1	X	High-Z

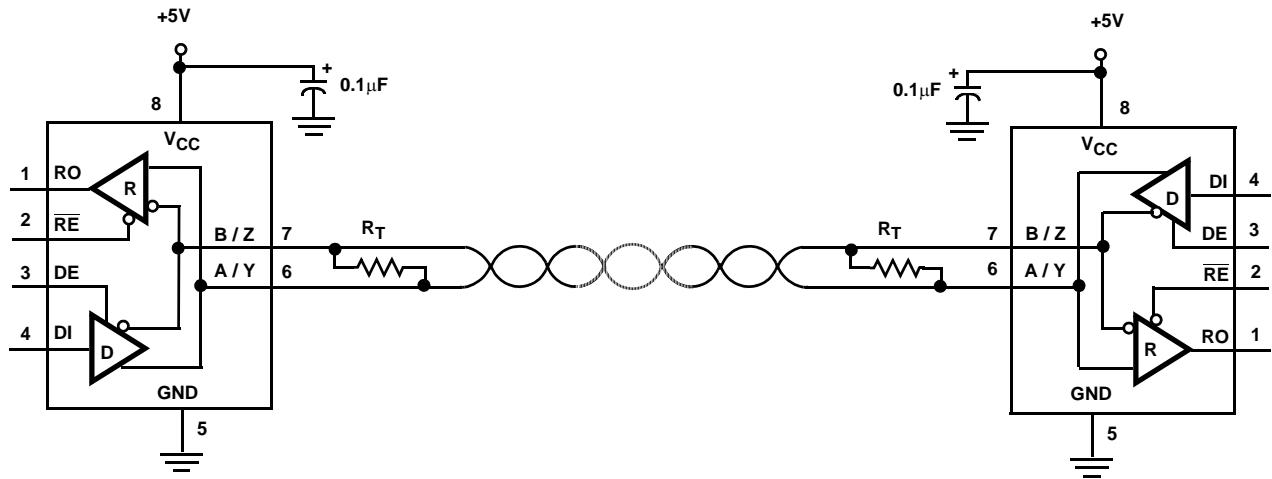
\*Shutdown Mode for ISL8483E (see Note 7)

## Pin Descriptions

PIN	FUNCTION
RO	Receiver output: If $A > B$ by at least 0.2V, RO is high; If $A < B$ by 0.2V or more, RO is low; RO = High if A and B are unconnected (floating).
$\overline{RE}$	Receiver output enable. RO is enabled when $\overline{RE}$ is low; RO is high impedance when $\overline{RE}$ is high.
DE	Driver output enable. The driver outputs, Y and Z, are enabled by bringing DE high. They are high impedance when DE is low.
DI	Driver input. A low on DI forces output Y low and output Z high. Similarly, a high on DI forces output Y high and output Z low.
GND	Ground connection.
A/Y	$\pm 15kV$ HBM ESD Protected, RS-485/422 level noninverting receiver input and noninverting driver output. Pin is an input (A) if DE = 0; pin is an output (Y) if DE = 1.
B/Z	$\pm 15kV$ HBM ESD Protected, RS-485/422 level inverting receiver input and inverting driver output. Pin is an input (B) if DE = 0; pin is an output (Z) if DE = 1.
V <sub>CC</sub>	System power supply input (4.5V to 5.5V).

## Typical Operating Circuits

ISL8483E, ISL8485E



### Absolute Maximum Ratings

V <sub>CC</sub> to Ground	7V
Input Voltages	
DI, DE, $\overline{RE}$	-0.5V to (V <sub>CC</sub> + 0.5V)
Input / Output Voltages	
A/Y, B/Z	-8V to +12.5V
RO	-0.5V to (V <sub>CC</sub> + 0.5V)
Short Circuit Duration	
Y, Z	Continuous
ESD Rating	See Specification Table

### Thermal Information

Thermal Resistance (Typical, Note 1)	$\theta_{JA}$ (°C/W)
8 Ld SOIC Package	170
8 Ld PDIP Package	140
Moisture Sensitivity (see Technical Brief TB363)	
All Packages	Level 1
Maximum Junction Temperature (Plastic Package)	150°C
Maximum Storage Temperature Range	-65°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300°C
(SOIC - Lead Tips Only)	

### Operating Conditions

Temperature Range	
ISL8485ECX	0°C to 70°C
ISL848XEIX	-40°C to 85°C

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTE:

1.  $\theta_{JA}$  is measured with the component mounted on a low effective thermal conductivity test board in free air. See Tech Brief TB379 for details.

### Electrical Specifications

Test Conditions: V<sub>CC</sub> = 4.5V to 5.5V; Unless Otherwise Specified.  
Typicals are at V<sub>CC</sub> = 5V, T<sub>A</sub> = 25°C, (Note 2)

PARAMETER	SYMBOL	TEST CONDITIONS	TEMP (°C)	MIN	TYP	MAX	UNITS
<b>DC CHARACTERISTICS</b>							
Driver Differential V <sub>OUT</sub> (no load)	V <sub>OD1</sub>		Full	-	-	V <sub>CC</sub>	V
Driver Differential V <sub>OUT</sub> (with load)	V <sub>OD2</sub>	R = 50Ω (RS-422), (Figure 1)	Full	2	3	-	V
		R = 27Ω (RS-485), (Figure 1)	Full	1.5	2.3	5	V
Change in Magnitude of Driver Differential V <sub>OUT</sub> for Complementary Output States	ΔV <sub>OD</sub>	R = 27Ω or 50Ω, (Figure 1)	Full	-	0.01	0.2	V
Driver Common-Mode V <sub>OUT</sub>	V <sub>OC</sub>	R = 27Ω or 50Ω, (Figure 1)	Full	-	-	3	V
Change in Magnitude of Driver Common-Mode V <sub>OUT</sub> for Complementary Output States	ΔV <sub>OC</sub>	R = 27Ω or 50Ω, (Figure 1)	Full	-	0.01	0.2	V
Logic Input High Voltage	V <sub>IH</sub>	DE, DI, $\overline{RE}$	Full	2	-	-	V
Logic Input Low Voltage	V <sub>IL</sub>	DE, DI, $\overline{RE}$	Full	-	-	0.8	V
Logic Input Current	I <sub>IN1</sub>	DE, DI, $\overline{RE}$ (ISL8483E)	Full	-2	-	2	μA
	I <sub>IN1</sub>	DI (ISL8485E)	Full	-2	-	2	μA
	I <sub>IN1</sub>	DE, $\overline{RE}$ (ISL8485E)	Full	-25	-	25	μA
Input Current (A, B), (Note 10)	I <sub>IN2</sub>	DE = 0V, V <sub>CC</sub> = 0V or 4.5 to 5.5V	Full	-	-	1	mA
		V <sub>IN</sub> = 12V	Full	-	-	-0.8	mA
Receiver Differential Threshold Voltage	V <sub>TH</sub>	-7V ≤ V <sub>CM</sub> ≤ 12V	Full	-0.2	-	0.2	V
Receiver Input Hysteresis	ΔV <sub>TH</sub>	V <sub>CM</sub> = 0V	25	-	70	-	mV
Receiver Output High Voltage	V <sub>OH</sub>	I <sub>O</sub> = -4mA, V <sub>ID</sub> = 200mV	Full	3.5	-	-	V
Receiver Output Low Voltage	V <sub>OL</sub>	I <sub>O</sub> = -4mA, V <sub>ID</sub> = 200mV	Full	-	-	0.4	V
Three-State (high impedance) Receiver Output Current	I <sub>OZR</sub>	0.4V ≤ V <sub>O</sub> ≤ 2.4V	Full	-	-	±1	μA
Receiver Input Resistance	R <sub>IN</sub>	-7V ≤ V <sub>CM</sub> ≤ 12V	Full	12	-	-	kΩ

# ISL8483E, ISL8485E

**Electrical Specifications** Test Conditions:  $V_{CC} = 4.5V$  to  $5.5V$ ; Unless Otherwise Specified.  
Typicals are at  $V_{CC} = 5V$ ,  $T_A = 25^{\circ}C$ , (Note 2) **(Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS	TEMP ( $^{\circ}C$ )	MIN	TYP	MAX	UNITS
No-Load Supply Current, (Note 3)	$I_{CC}$	ISL8485E, DI, $\overline{RE} = 0V$ or $V_{CC}$	DE = $V_{CC}$	Full	-	550	900 $\mu A$
			DE = 0V	Full	-	340	500 $\mu A$
		ISL8483E, DI, $\overline{RE} = 0V$ or $V_{CC}$	DE = $V_{CC}$	Full	-	390	650 $\mu A$
			DE = 0V	Full	-	160	250 $\mu A$
Shutdown Supply Current	$I_{SHDN}$	ISL8483E, DE = 0V, $\overline{RE} = V_{CC}$ , DI = 0V or $V_{CC}$	Full	-	1	50	nA
Driver Short-Circuit Current, $V_O =$ High or Low	$I_{OSD1}$	DE = $V_{CC}$ , $-7V \leq V_Y$ or $V_Z \leq 12V$ , (Note 4)	Full	35	-	250	mA
Receiver Short-Circuit Current	$I_{OSR}$	$0V \leq V_O \leq V_{CC}$	Full	7	-	85	mA
<b>SWITCHING CHARACTERISTICS (ISL8485E)</b>							
Driver Input to Output Delay	$t_{PLH}, t_{PHL}$	$R_{DIFF} = 54\Omega$ , $C_L = 100pF$ , (Figure 2)	Full	18	30	50	ns
Driver Output Skew	$t_{SKEW}$	$R_{DIFF} = 54\Omega$ , $C_L = 100pF$ , (Figure 2)	Full	-	2	10	ns
Driver Differential Rise or Fall Time	$t_R, t_F$	$R_{DIFF} = 54\Omega$ , $C_L = 100pF$ , (Figure 2)	Full	3	11	25	ns
Driver Enable to Output High	$t_{ZH}$	$C_L = 100pF$ , SW = GND, (Figure 3)	Full	-	17	70	ns
Driver Enable to Output Low	$t_{ZL}$	$C_L = 100pF$ , SW = $V_{CC}$ , (Figure 3)	Full	-	14	70	ns
Driver Disable from Output High	$t_{HZ}$	$C_L = 15pF$ , SW = GND, (Figure 3)	Full	-	19	70	ns
Driver Disable from Output Low	$t_{LZ}$	$C_L = 15pF$ , SW = $V_{CC}$ , (Figure 3)	Full	-	13	70	ns
Receiver Input to Output Delay	$t_{PLH}, t_{PHL}$	(Figure 4)	Full	30	40	150	ns
Receiver Skew   $t_{PLH} - t_{PHL}$	$t_{SKD}$	(Figure 4)	25	-	5	-	ns
Receiver Enable to Output High	$t_{ZH}$	$C_L = 15pF$ , SW = GND, (Figure 5)	Full	-	9	50	ns
Receiver Enable to Output Low	$t_{ZL}$	$C_L = 15pF$ , SW = $V_{CC}$ , (Figure 5)	Full	-	9	50	ns
Receiver Disable from Output High	$t_{HZ}$	$C_L = 15pF$ , SW = GND, (Figure 5)	Full	-	9	50	ns
Receiver Disable from Output Low	$t_{LZ}$	$C_L = 15pF$ , SW = $V_{CC}$ , (Figure 5)	Full	-	9	50	ns
Maximum Data Rate	$f_{MAX}$		Full	5	-	-	Mbps
<b>SWITCHING CHARACTERISTICS (ISL8483E)</b>							
Driver Input to Output Delay	$t_{PLH}, t_{PHL}$	$R_{DIFF} = 54\Omega$ , $C_L = 100pF$ , (Figure 2)	Full	250	800	2000	ns
Driver Output Skew	$t_{SKEW}$	$R_{DIFF} = 54\Omega$ , $C_L = 100pF$ , (Figure 2)	Full	-	160	800	ns
Driver Differential Rise or Fall Time	$t_R, t_F$	$R_{DIFF} = 54\Omega$ , $C_L = 100pF$ , (Figure 2)	Full	250	800	2000	ns
Driver Enable to Output High	$t_{ZH}$	$C_L = 100pF$ , SW = GND, (Figure 3), (Note 5)	Full	250	-	2000	ns
Driver Enable to Output Low	$t_{ZL}$	$C_L = 100pF$ , SW = $V_{CC}$ , (Figure 3), (Note 5)	Full	250	-	2000	ns
Driver Disable from Output High	$t_{HZ}$	$C_L = 15pF$ , SW = GND, (Figure 3)	Full	300	-	3000	ns
Driver Disable from Output Low	$t_{LZ}$	$C_L = 15pF$ , SW = $V_{CC}$ , (Figure 3)	Full	300	-	3000	ns
Receiver Input to Output Delay	$t_{PLH}, t_{PHL}$	(Figure 4)	Full	250	350	2000	ns
Receiver Skew   $t_{PLH} - t_{PHL}$	$t_{SKD}$	(Figure 4)	25	-	25	-	ns
Receiver Enable to Output High	$t_{ZH}$	$C_L = 15pF$ , SW = GND, (Figure 5), (Note 6)	Full	-	10	50	ns
Receiver Enable to Output Low	$t_{ZL}$	$C_L = 15pF$ , SW = $V_{CC}$ , (Figure 5), (Note 6)	Full	-	10	50	ns
Receiver Disable from Output High	$t_{HZ}$	$C_L = 15pF$ , SW = GND, (Figure 5)	Full	-	10	50	ns
Receiver Disable from Output Low	$t_{LZ}$	$C_L = 15pF$ , SW = $V_{CC}$ , (Figure 5)	Full	-	10	50	ns
Maximum Data Rate	$f_{MAX}$		Full	250	-	-	kbps
Time to Shutdown	$t_{SHDN}$	(Note 7)	Full	50	200	600	ns
Driver Enable from Shutdown to Output High	$t_{ZH(SHDN)}$	$C_L = 100pF$ , SW = GND, (Figure 3), (Notes 7, 8)	Full	-	-	2000	ns

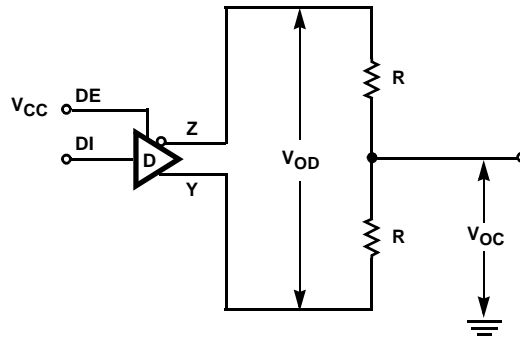
**Electrical Specifications** Test Conditions:  $V_{CC} = 4.5V$  to  $5.5V$ ; Unless Otherwise Specified.  
Typicals are at  $V_{CC} = 5V$ ,  $T_A = 25^{\circ}C$ , (Note 2) **(Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS	TEMP ( $^{\circ}C$ )	MIN	TYP	MAX	UNITS
Driver Enable from Shutdown to Output Low	$t_{ZL}(SHDN)$	$C_L = 100pF$ , $SW = V_{CC}$ , (Figure 3), (Notes 7, 8)	Full	-	-	2000	ns
Receiver Enable from Shutdown to Output High	$t_{ZH}(SHDN)$	$C_L = 15pF$ , $SW = GND$ , (Figure 5), (Notes 7, 9)	Full	-	-	2500	ns
Receiver Enable from Shutdown to Output Low	$t_{ZL}(SHDN)$	$C_L = 15pF$ , $SW = V_{CC}$ , (Figure 5), (Notes 7, 9)	Full	-	-	2500	ns
<b>ESD PERFORMANCE</b>							
RS-485 Pins (A/Y, B/Z)		Human Body Model	25	-	$\pm 15$	-	kV
All Other Pins			25	-	$>\pm 7$	-	kV

NOTE:

- All currents into device pins are positive; all currents out of device pins are negative. All voltages are referenced to device ground unless otherwise specified.
- Supply current specification is valid for loaded drivers when  $DE = 0V$ .
- Applies to peak current. See "Typical Performance Curves" for more information.
- When testing the ISL8483E, keep  $\overline{RE} = 0$  to prevent the device from entering SHDN.
- When testing the ISL8483E, the  $\overline{RE}$  signal high time must be short enough (typically  $<200ns$ ) to prevent the device from entering SHDN.
- The ISL8483E is put into shutdown by bringing  $\overline{RE}$  high and  $DE$  low. If the inputs are in this state for less than  $50ns$ , the parts are guaranteed not to enter shutdown. If the inputs are in this state for at least  $600ns$ , the parts are guaranteed to have entered shutdown. See "Low-Power Shutdown Mode" section.
- Keep  $\overline{RE} = V_{CC}$ , and set the  $DE$  signal low time  $>600ns$  to ensure that the device enters SHDN.
- Set the  $\overline{RE}$  signal high time  $>600ns$  to ensure that the device enters SHDN.
- Devices meeting these limits are denoted as "single unit load (1 UL)" transceivers. The RS-485 standard allows up to 32 Unit Loads on the bus.

## Test Circuits and Waveforms



**FIGURE 1. DRIVER  $V_{OD}$  AND  $V_{OC}$**

Test Circuits and Waveforms (Continued)

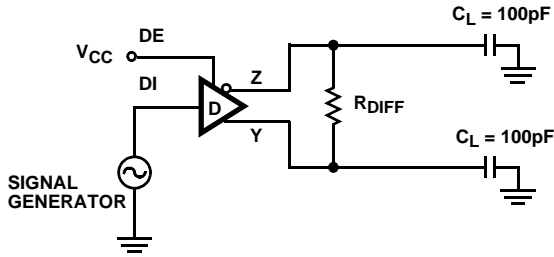
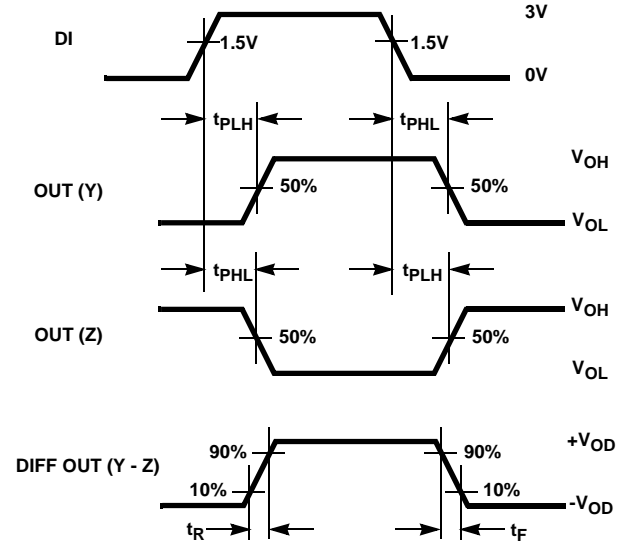


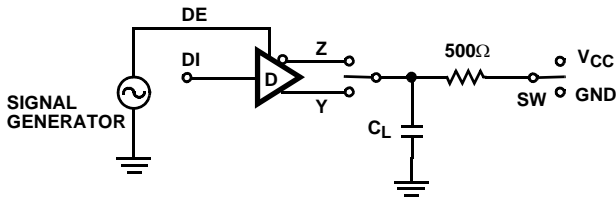
FIGURE 2A. TEST CIRCUIT



$$\text{SKEW} = |t_{PLH}(Y \text{ or } Z) - t_{PHL}(Z \text{ or } Y)|$$

FIGURE 2B. MEASUREMENT POINTS

FIGURE 2. DRIVER PROPAGATION DELAY AND DIFFERENTIAL TRANSITION TIMES



(SHDN) FOR ISL8483E ONLY

PARAMETER	OUTPUT	$\overline{RE}$	DI	SW	$C_L$ (pF)
$t_{HZ}$	Y/Z	X	1 / 0	GND	15
$t_{LZ}$	Y/Z	X	0 / 1	$V_{CC}$	15
$t_{ZH}$	Y/Z	0 (Note 5)	1 / 0	GND	100
$t_{ZL}$	Y/Z	0 (Note 5)	0 / 1	$V_{CC}$	100
$t_{ZH}(\text{SHDN})$	Y/Z	1 (Note 8)	1 / 0	GND	100
$t_{ZL}(\text{SHDN})$	Y/Z	1 (Note 8)	0 / 1	$V_{CC}$	100

FIGURE 3A. TEST CIRCUIT

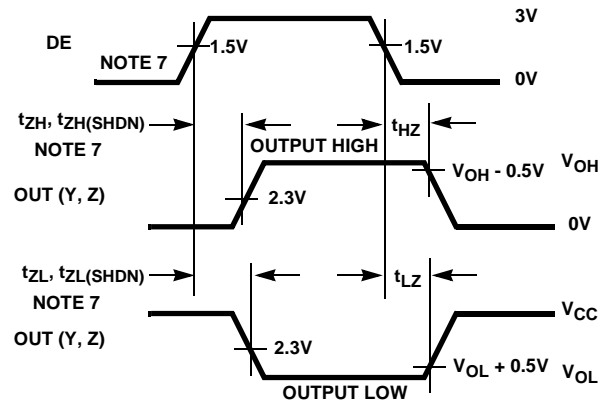


FIGURE 3B. MEASUREMENT POINTS

FIGURE 3. DRIVER ENABLE AND DISABLE TIMES

## Test Circuits and Waveforms (Continued)

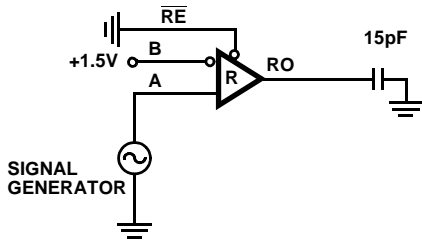


FIGURE 4A. TEST CIRCUIT

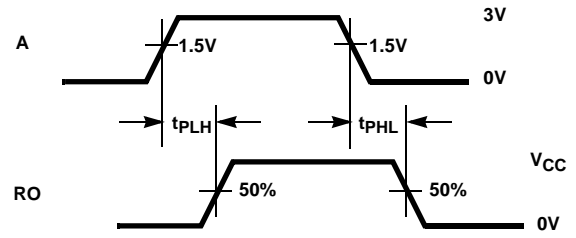
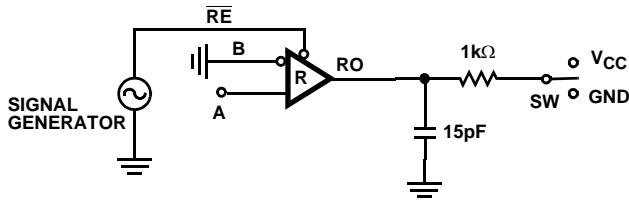


FIGURE 4B. MEASUREMENT POINTS

FIGURE 4. RECEIVER PROPAGATION DELAY



(SHDN) FOR ISL8483E ONLY

PARAMETER	DE	A	SW
$t_{HZ}$	0	+1.5V	GND
$t_{LZ}$	0	-1.5V	$V_{CC}$
$t_{ZH}$ (Note 6)	0	+1.5V	GND
$t_{ZL}$ (Note 6)	0	-1.5V	$V_{CC}$
$t_{ZH}(SHDN)$ (Note 9)	0	+1.5V	GND
$t_{ZL}(SHDN)$ (Note 9)	0	-1.5V	$V_{CC}$

FIGURE 5A. TEST CIRCUIT

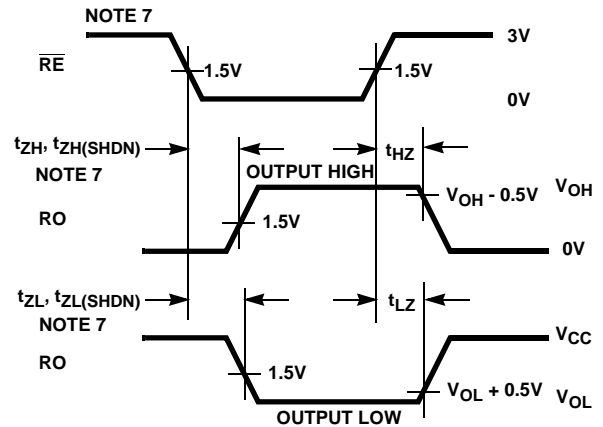


FIGURE 5B. MEASUREMENT POINTS

FIGURE 5. RECEIVER ENABLE AND DISABLE TIMES

## Application Information

RS-485 and RS-422 are differential (balanced) data transmission standards for use in long haul or noisy environments. RS-422 is a subset of RS-485, so RS-485 transceivers are also RS-422 compliant. RS-422 is a point-to-multipoint (multidrop) standard, which allows only one driver and up to 10 (assuming one unit load devices) receivers on each bus. RS-485 is a true multipoint standard, which allows up to 32 one unit load devices (any combination of drivers and receivers) on each bus. To allow for multipoint operation, the RS-485 spec requires that drivers must handle bus contention without sustaining any damage.

Another important advantage of RS-485 is the extended common mode range (CMR), which specifies that the driver outputs and receiver inputs withstand signals that range from +12V to -7V. RS-422 and RS-485 are intended for runs as long as 4000', so the wide CMR is necessary to handle

ground potential differences, as well as voltages induced in the cable by external fields.

## Receiver Features

These devices utilize a differential input receiver for maximum noise immunity and common mode rejection. Input sensitivity is  $\pm 200\text{mV}$ , as required by the RS422 and RS-485 specifications.

Receiver input impedance surpasses the RS-422 spec of  $4\text{k}\Omega$ , and meets the RS-485 "Unit Load" requirement of  $12\text{k}\Omega$  minimum.

Receiver inputs function with common mode voltages as great as  $\pm 7\text{V}$  outside the power supplies (i.e., +12V and -7V), making them ideal for long networks where induced voltages are a realistic concern.

All the receivers include a "fail-safe if open" function that guarantees a high level receiver output if the receiver inputs are unconnected (floating).



Receivers easily meet the data rates supported by the corresponding driver.

ISL8483E/85E receiver outputs are three-statable via the active low  $\overline{RE}$  input.

### **Driver Features**

The RS-485/422 driver is a differential output device that delivers at least 1.5V across a  $54\Omega$  load (RS-485), and at least 2V across a  $100\Omega$  load (RS-422). The drivers feature low propagation delay skew to maximize bit width, and to minimize EMI.

Drivers of the ISL8483E/85E are three-statable via the active high DE input.

The ISL8483E driver outputs are slew rate limited to minimize EMI, and to minimize reflections in unterminated or improperly terminated networks. Data rate on these slew rate limited versions is a maximum of 250kbps. Outputs of the ISL8485E driver are not limited, so faster output transition times allow data rates of at least 5Mbps.

### **Data Rate, Cables, and Terminations**

RS-485/422 are intended for network lengths up to 4000', but the maximum system data rate decreases as the transmission length increases. Devices operating at 5Mbps are limited to lengths less than 100', while the 250kbps versions can operate at full data rates with lengths in excess of 1000'.

Twisted pair is the cable of choice for RS-485/422 networks. Twisted pair cables tend to pick up noise and other electromagnetically induced voltages as common mode signals, which are effectively rejected by the differential receivers in these ICs.

Proper termination is imperative, when using the 5Mbps devices, to minimize reflections. Short networks using the 250kbps versions need not be terminated, but, terminations are recommended unless power dissipation is an overriding concern.

In point-to-point, or point-to-multipoint (single driver on bus) networks, the main cable should be terminated in its characteristic impedance (typically  $120\Omega$ ) at the end farthest from the driver. In multi-receiver applications, stubs connecting receivers to the main cable should be kept as short as possible. Multipoint (multi-driver) systems require that the main cable be terminated in its characteristic impedance at both ends. Stubs connecting a transceiver to the main cable should be kept as short as possible.

### **Built-In Driver Overload Protection**

As stated previously, the RS-485 spec requires that drivers survive worst case bus contentions undamaged. The ISL848XE devices meet this requirement via driver output short circuit current limits, and on-chip thermal shutdown circuitry.

The driver output stages incorporate short circuit current limiting circuitry which ensures that the output current never

exceeds the RS-485 spec, even at the common mode voltage range extremes. Additionally, these devices utilize a foldback circuit which reduces the short circuit current, and thus the power dissipation, whenever the contending voltage exceeds either supply.

In the event of a major short circuit condition, ISL848XE devices also include a thermal shutdown feature that disables the drivers whenever the die temperature becomes excessive. This eliminates the power dissipation, allowing the die to cool. The drivers automatically reenables after the die temperature drops about 15 degrees. If the contention persists, the thermal shutdown/reenable cycle repeats until the fault is cleared. Receivers stay operational during thermal shutdown.

### **Low Power Shutdown Mode (ISL8483E Only)**

These CMOS transceivers all use a fraction of the power required by their bipolar counterparts, but the ISL8483E includes a shutdown feature that reduces the already low quiescent  $I_{CC}$  to a 1nA trickle. The ISL8483E enters shutdown whenever the receiver and driver are **simultaneously** disabled ( $\overline{RE} = V_{CC}$  and  $DE = GND$ ) for a period of at least 600ns. Disabling both the driver and the receiver for less than 50ns guarantees that the ISL8483E will not enter shutdown.

Note that receiver and driver enable times increase when the ISL8483E enables from shutdown. Refer to Notes 5-8, at the end of the Electrical Specification table, for more information.

### **ESD Protection**

All pins on these interface devices include class 3 Human Body Model (HBM) ESD protection structures, but the RS-485 pins (driver outputs and receiver inputs) incorporate advanced structures allowing them to survive ESD events in excess of  $\pm 15kV$  HBM. The RS-485 pins are particularly vulnerable to ESD damage because they typically connect to an exposed port on the exterior of the finished product. Simply touching the port pins, or connecting a cable, can cause an ESD event that might destroy unprotected ICs. These new ESD structures protect the device whether or not it is powered up, protect without allowing any latchup mechanism to activate, and without degrading the RS-485 common mode range of -7V to +12V. This built-in ESD protection eliminates the need for board level protection structures (e.g., transient suppression diodes), and the associated, undesirable capacitive load they present.

### **Human Body Model Testing**

As the name implies, this test method emulates the ESD event delivered to an IC during human handling. The tester delivers the charge stored on a 100pF capacitor through a 1.5k $\Omega$  current limiting resistor into the pin under test. The HBM method determines an IC's ability to withstand the ESD events typically present during handling and manufacturing.

The RS-485 pin survivability on this high ESD family has been characterized to be in excess of  $\pm 15kV$ , for discharges to GND.

**Typical Performance Curves**  $V_{CC} = 5V$ ,  $T_A = 25^{\circ}C$ , ISL8483E and ISL8485E; Unless Otherwise Specified

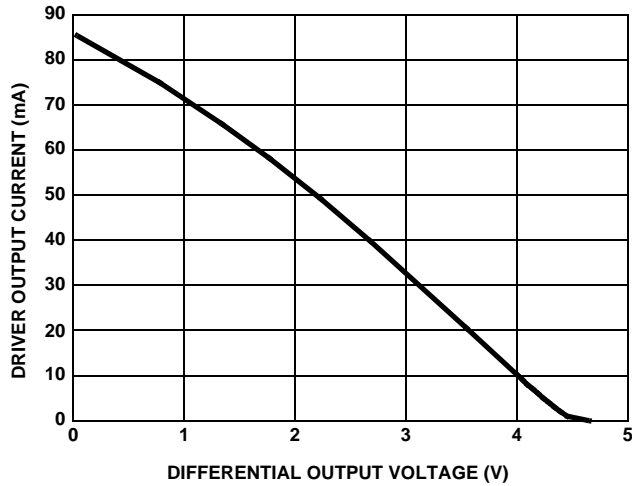


FIGURE 6. DRIVER OUTPUT CURRENT vs DIFFERENTIAL OUTPUT VOLTAGE

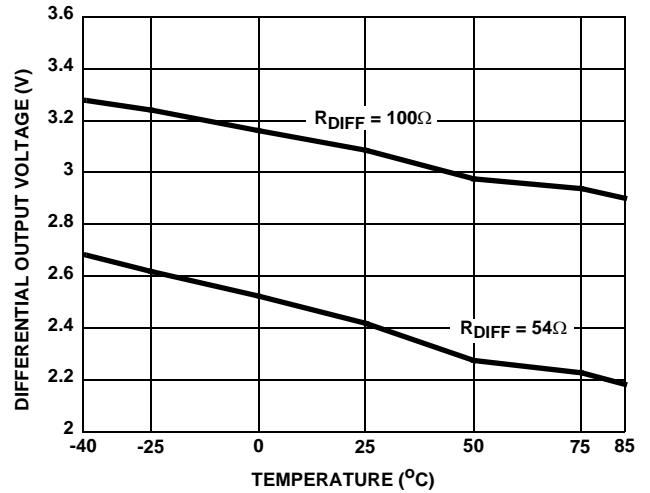


FIGURE 7. DRIVER DIFFERENTIAL OUTPUT VOLTAGE vs TEMPERATURE

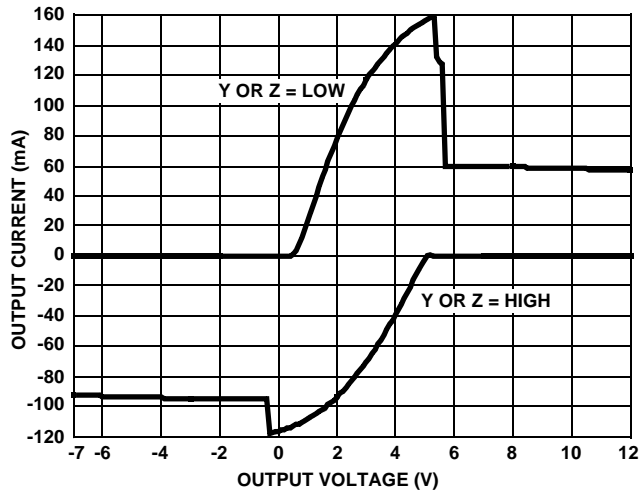


FIGURE 8. DRIVER OUTPUT CURRENT vs SHORT CIRCUIT VOLTAGE

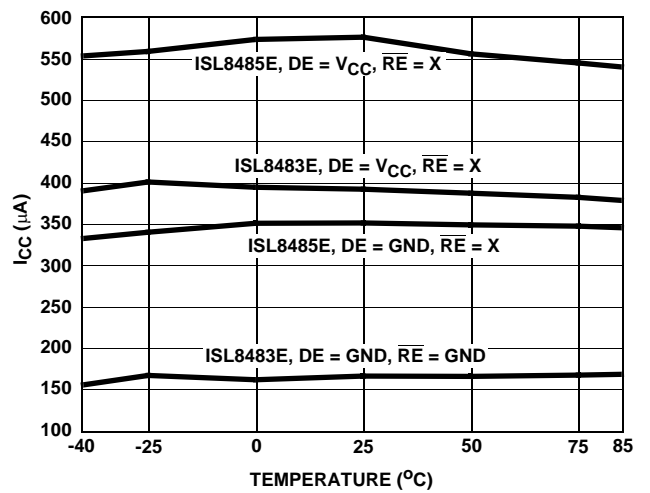


FIGURE 9. SUPPLY CURRENT vs TEMPERATURE

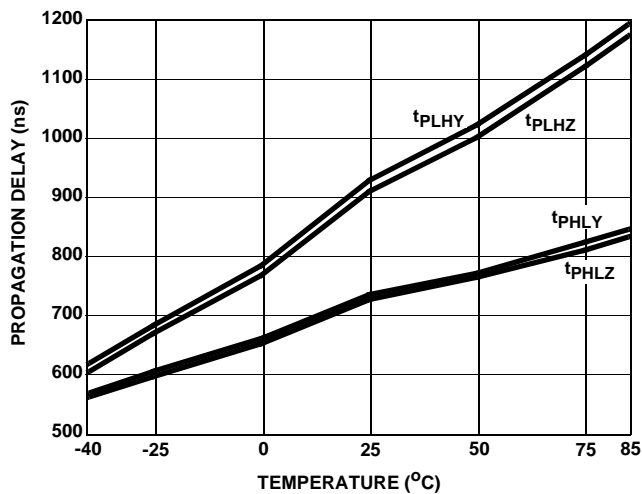


FIGURE 10. DRIVER PROPAGATION DELAY vs TEMPERATURE (ISL8483E)

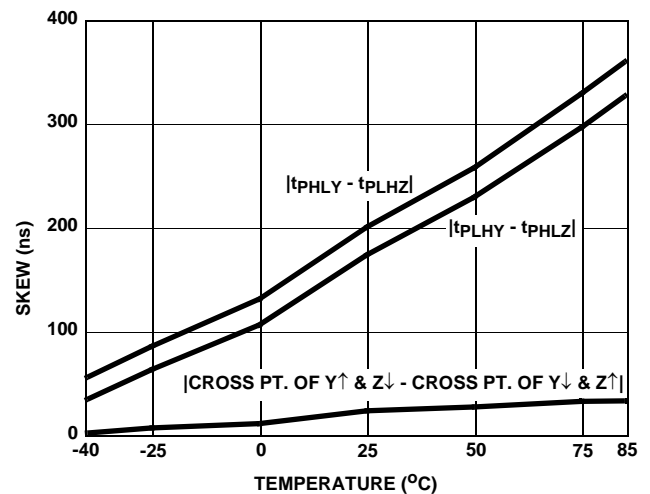


FIGURE 11. DRIVER SKEW vs TEMPERATURE (ISL8483E)

**Typical Performance Curves**  $V_{CC} = 5V$ ,  $T_A = 25^\circ C$ , ISL8483E and ISL8485E; Unless Otherwise Specified (Continued)

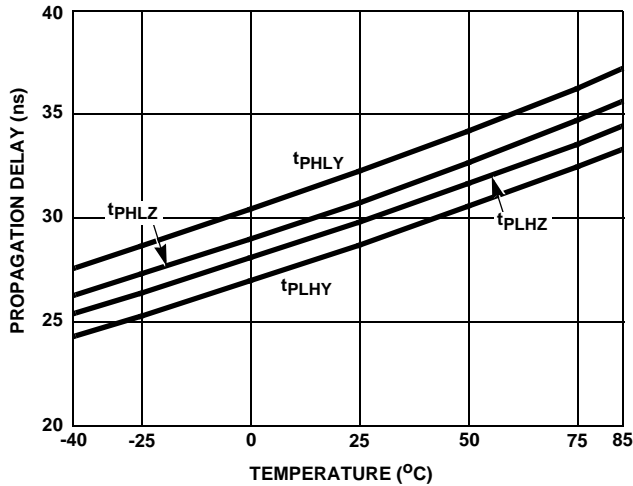


FIGURE 12. DRIVER PROPAGATION DELAY vs TEMPERATURE (ISL8485E)

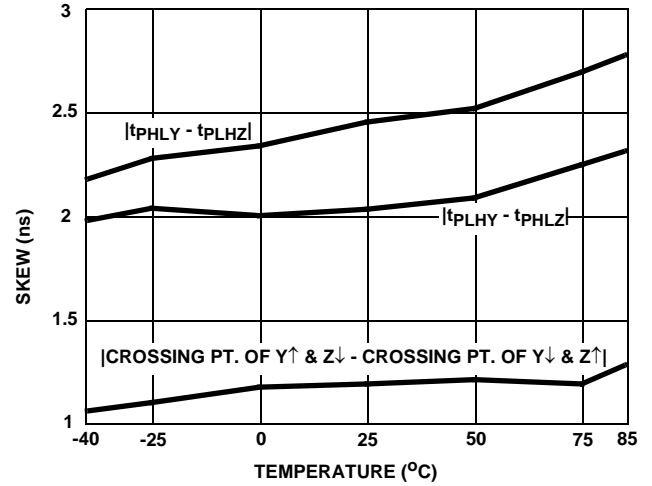


FIGURE 13. DRIVER SKEW vs TEMPERATURE (ISL8485E)

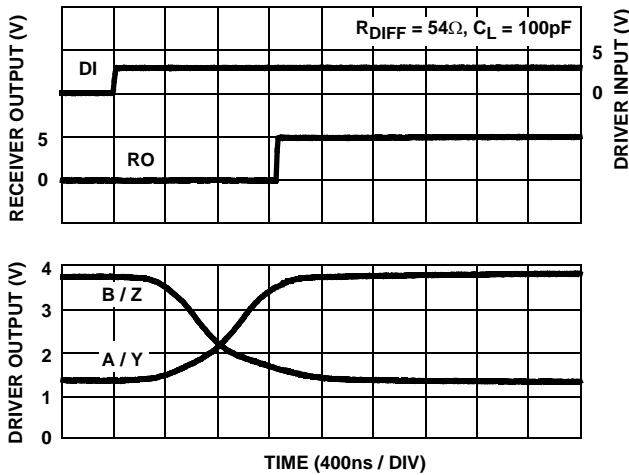


FIGURE 14. DRIVER AND RECEIVER WAVEFORMS, LOW TO HIGH (ISL8483E)

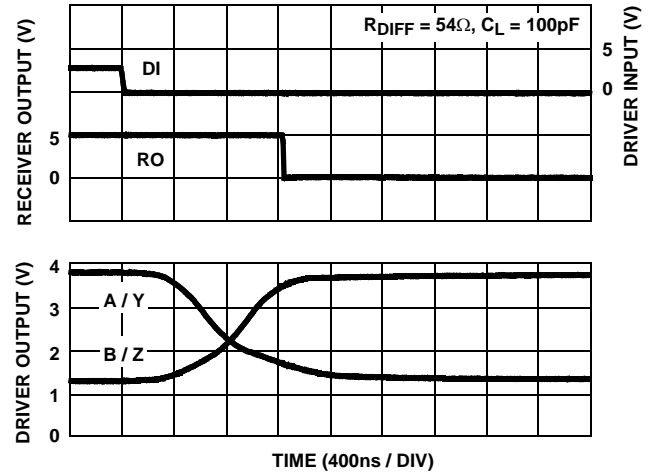


FIGURE 15. DRIVER AND RECEIVER WAVEFORMS, HIGH TO LOW (ISL8483E)

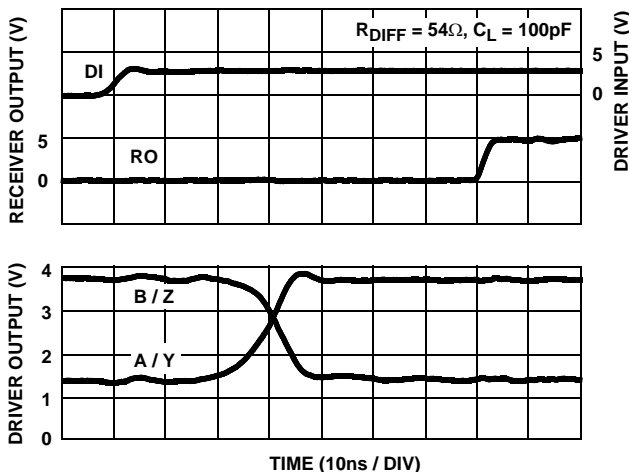


FIGURE 16. DRIVER AND RECEIVER WAVEFORMS, LOW TO HIGH (ISL8485E)

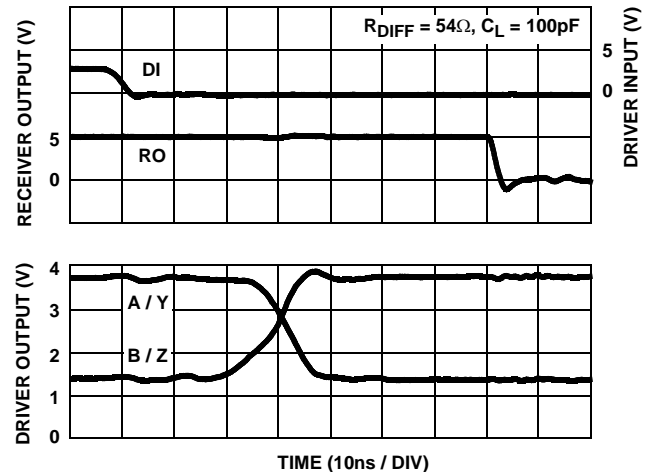


FIGURE 17. DRIVER AND RECEIVER WAVEFORMS, HIGH TO LOW (ISL8485E)

***Die Characteristics***

**SUBSTRATE POTENTIAL (POWERED UP):**

GND

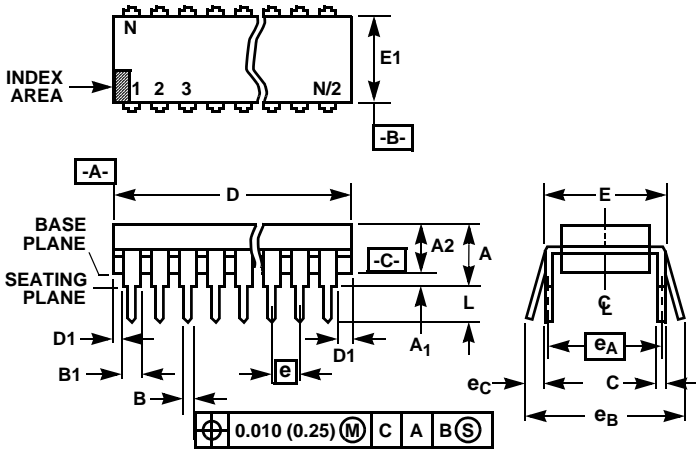
**TRANSISTOR COUNT:**

518

**PROCESS:**

Si Gate CMOS

## Dual-In-Line Plastic Packages (PDIP)



### NOTES:

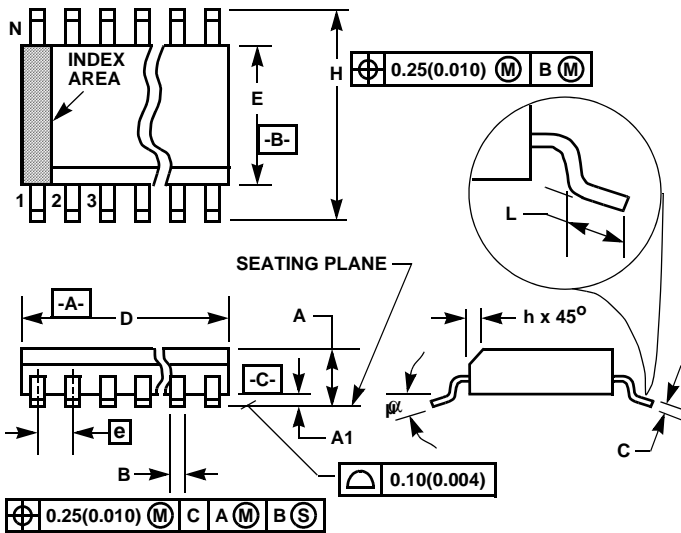
1. Controlling Dimensions: INCH. In case of conflict between English and Metric dimensions, the inch dimensions control.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication No. 95.
4. Dimensions A, A1 and L are measured with the package seated in JEDEC seating plane gauge GS-3.
5. D, D1, and E1 dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 inch (0.25mm).
6. E and  $e_A$  are measured with the leads constrained to be perpendicular to datum  $-C-$ .
7.  $e_B$  and  $e_C$  are measured at the lead tips with the leads unconstrained.  $e_C$  must be zero or greater.
8. B1 maximum dimensions do not include dambar protrusions. Dambar protrusions shall not exceed 0.010 inch (0.25mm).
9. N is the maximum number of terminal positions.
10. Corner leads (1, N, N/2 and N/2 + 1) for E8.3, E16.3, E18.3, E28.3, E42.6 will have a B1 dimension of 0.030 - 0.045 inch (0.76 - 1.14mm).

### E8.3 (JEDEC MS-001-BA ISSUE D) 8 LEAD DUAL-IN-LINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.210	-	5.33	4
A1	0.015	-	0.39	-	4
A2	0.115	0.195	2.93	4.95	-
B	0.014	0.022	0.356	0.558	-
B1	0.045	0.070	1.15	1.77	8, 10
C	0.008	0.014	0.204	0.355	-
D	0.355	0.400	9.01	10.16	5
D1	0.005	-	0.13	-	5
E	0.300	0.325	7.62	8.25	6
E1	0.240	0.280	6.10	7.11	5
e	0.100 BSC		2.54 BSC		-
$e_A$	0.300 BSC		7.62 BSC		6
$e_B$	-	0.430	-	10.92	7
L	0.115	0.150	2.93	3.81	4
N	8		8		9

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# Small Outline Plastic Packages (SOIC)



## NOTES:

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch).
10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

## M8.15 (JEDEC MS-012-AA ISSUE C) 8 LEAD NARROW BODY SMALL OUTLINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.0532	0.0688	1.35	1.75	-
A1	0.0040	0.0098	0.10	0.25	-
B	0.013	0.020	0.33	0.51	9
C	0.0075	0.0098	0.19	0.25	-
D	0.1890	0.1968	4.80	5.00	3
E	0.1497	0.1574	3.80	4.00	4
e	0.050 BSC		1.27 BSC		-
H	0.2284	0.2440	5.80	6.20	-
h	0.0099	0.0196	0.25	0.50	5
L	0.016	0.050	0.40	1.27	6
N	8		8		7
α	0°	8°	0°	8°	-

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